



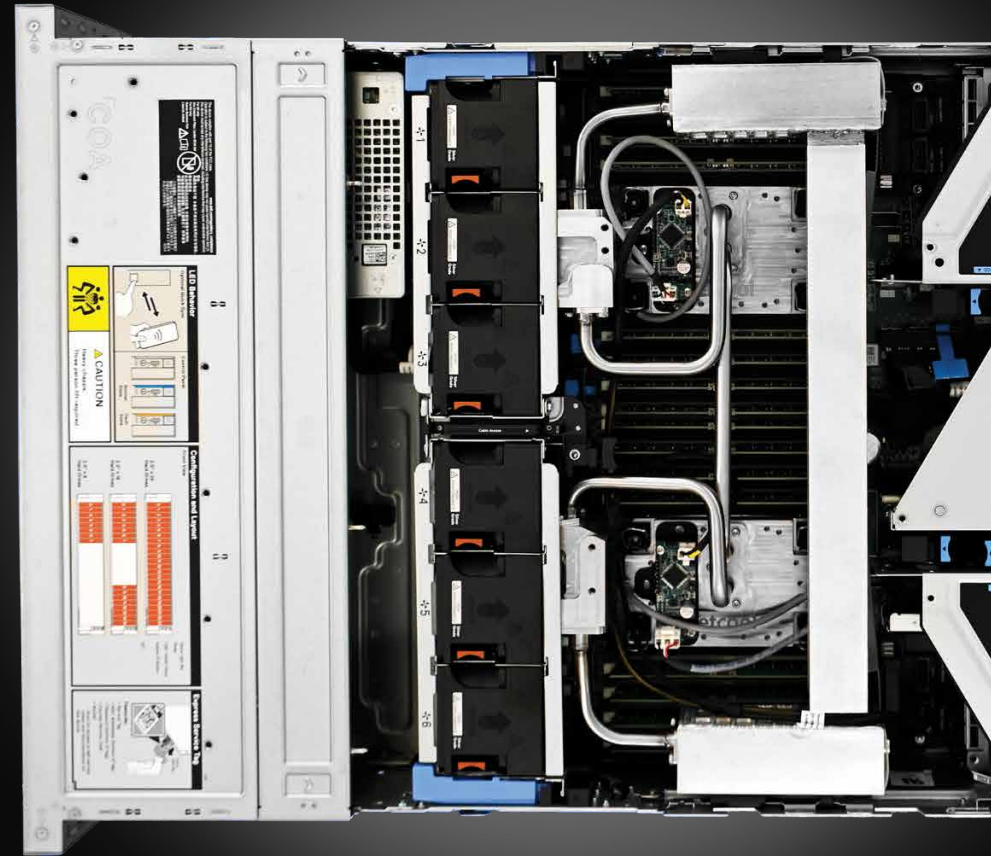
SmartPlate System for Dell PowerEdge R770 Servers

Maximize Power Budgets with Self-Contained Liquid Cooling

JetCool's SmartPlate System for the Dell PowerEdge R770 server is a self-contained liquid cooling solution that enables immediate value for customers, delivering an average of **13% power savings with no facility piping or plumbing needed**. Popular with compute-intensive verticals ranging from federal and energy to finance, it allows customers to deploy the latest processors in air-cooled facilities without the need for complex infrastructure upgrades.

How does it work?

Engineered per server, the system uses precision cold plates to remove heat from the processors within a closed loop, rejecting heat through an integrated liquid-to-air radiator into the data center hall. Because the system is fully self-contained, it doesn't require facility water systems (FWS) or infrastructure upgrades, enabling a seamless, nondisruptive deployment for latency and uptime-sensitive environments.



— POWERED BY —
DELL Technologies

For more Information and Pricing, Contact Us
hello@jetcool.com | (978) 449-4600 | jetcool.com

Dell PowerEdge R770 Datasheet

Uncomplicate Liquid Cooling

Achieve peak server performance with SmartPlate System:

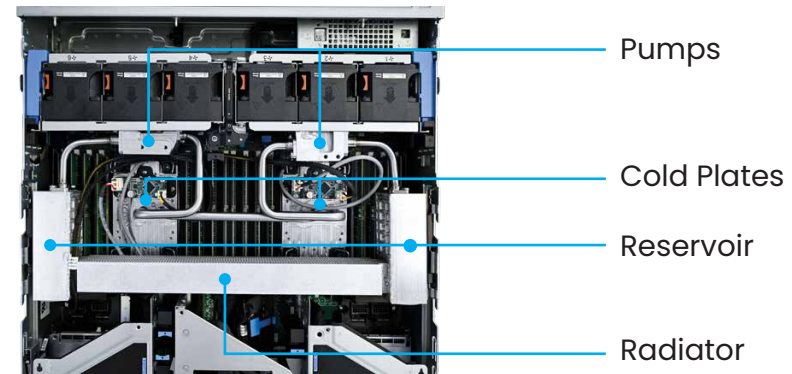
- **Temperature Management:** Experience chipset temperatures that are 15% cooler than stock air-cooled servers.
- **Power Efficiency:** SmartPlate System cuts fan speeds 50%, delivering 13% average server power savings
- **Noise Reduction:** Achieve a quieter operational environment with a significant 60% lower noise level.
- **Adaptable Environment Tolerance:** Achieve optimal performance even in challenging conditions, cooling effectively in environments exceeding 35°C.
- **Rapid Deployment:** A drop-in replacement for heat sinks that installs quickly and allows individual server upgrade and installation.

Experience hassle-free liquid cooling for your servers with zero maintenance throughout their lifetime and no modifications needed for your facilities. **Cool smarter, not harder.**

Product Specifications

Description	Value
Processor Compatibility	Intel Xeon 6
SmartPlate Dimensions	118 mm(L) x 78 mm (W) x 9.3 mm (H) *length and width determined by socket size
System Weight	3100 g
Form Factor	2U
Supply Power	12 W @ 12 V
TDP Rating	Up to 1,500 W
Coolant Fluid	PG25; Water-based coolants
Survival Temperature	0°C to 45°C

System Overview



Patented Technology, Additional Patents Pending